

Amendments to the Claims

Claims 1 and 2 (Canceled).

3. (Original): A substrate susceptor for receiving a semiconductor substrate to be deposited upon by thermal deposition comprising susceptor back side radiant heating, the susceptor comprising a body having a front substrate receiving side, a back side, and a peripheral edge; the body comprising multiple materials having at least two different thermal conductivities; an outer material received across the back side having a higher thermal conductivity than an immediately adjacent material of the body, the outer material comprising at least one of polycrystalline diamond and copper.

Claims 4-12 (Canceled).

13. (Currently Amended): A substrate susceptor for receiving physically supporting a semiconductor substrate to be deposited upon, the susceptor comprising a body having a front substrate receiving side face comprising a bearing surface to physically support the semiconductor substrate to be deposited upon, a back side face, and a peripheral edge; the body comprising a ring having a radial inner portion at least a radial majority of which is non-solid space extending from the front side face to the back side face, the bearing surface being received on said ring.

Claims 14-22 (Canceled).

23. (New): The substrate susceptor of claim 3 wherein the outer material comprises copper.

24. (New): The substrate susceptor of claim 3 wherein the outer material comprises polycrystalline diamond.

25. (New): The substrate susceptor of claim 3 wherein the body over which said outer material is received comprises SiC coated graphite.

26. (New): The substrate susceptor of claim 3 wherein the outer material is not received over any outer portion of any of the front substrate receiving side.

27. (New): The substrate susceptor of claim 3 wherein the outer material comprises an outermost material of the back side.

28. (New): The substrate susceptor of claim 3 wherein the outer material is of uniform thickness over the back side.

29. (New): The substrate susceptor of claim 3 wherein the outer material is of non-uniform thickness over the back side.

30. (New): The substrate susceptor of claim 29 wherein the outer material has greatest thickness within a back side incident radiant heating overlap area.

31. (New): The substrate susceptor of claim 13 wherein the ring has a radially innermost surface which is continuous and round.

32. (New): The substrate susceptor of claim 13 wherein the radial inner portion is centered relative to the body.

33. (New): The substrate susceptor of claim 13 wherein the non-solid space is sized such that at least a majority of said substrate to be deposited upon will overlie said non-solid space.

34. (New): The substrate susceptor of claim 33 wherein the non-solid space is sized such that at least 90% of said substrate to be deposited upon will overlie said non-solid space.

35. (New): The substrate susceptor of claim 34 wherein the non-solid space is sized such that at least 95% of said substrate to be deposited upon will overlie said non-solid space.

36. (New): The substrate susceptor of claim 13 wherein all of the radial inner portion is non-solid space.

37. (New): The substrate susceptor of claim 13 wherein only a portion of the radial inner portion is non-solid space.

38. (New): The substrate susceptor of claim 37 comprising at least one cross piece extending across the radial inner portion.

39. (New): The substrate susceptor of claim 38 wherein said cross piece is opaque to infrared radiation.

40. (New): The substrate susceptor of claim 38 wherein said cross piece is transparent to infrared radiation.

41. (New): The substrate susceptor of claim 37 comprising at least two cross pieces extending across the radial inner portion.

42. (New): The substrate susceptor of claim 41 wherein said cross pieces are opaque to infrared radiation.

43. (New): The substrate susceptor of claim 41 wherein said cross pieces are transparent to infrared radiation.